

Intel® Compute Stick STK1AW32SC

STK1A32SC

Technical Product Specification

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Revision History

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001	First release	November 2015
002	Changed URL for BIOS Update and BIOS Recovery information	January 2016
003	Corrected MTBF number	January 2016
004	Added Section 2.3 Mechanical Considerations and updated Section 2.4 Reliability	February 2016
005	Corrected the headers	March 2016
006	Updated Section 1.3 Operating System Overview and Table 4	May 2016
007	Updated processor and operating system information	June 2016
008	Updated HDMI audio information	October 2017

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This product specification applies to only the standard Intel® Compute Stick with BIOS identifier SCCHTAX5.86A.

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Preface

This Technical Product Specification (TPS) specifies the layout, components, connectors, power and environmental requirements, and the BIOS for Intel Compute Stick STK1AW32SC and STK1A32SC.



NOTE

In this document, the use of "Intel Compute Stick" will refer to the STK1AW32SC and STK1A32SC versions of the Intel Compute Stick.

Intended Audience

The TPS is intended to provide detailed technical information about Intel Compute Stick STK1AW32SC and STK1A32SC and its components to the vendors, system integrators, and other engineers and technicians who need this level of information. It is specifically *not* intended for general audiences.

What This Document Contains

Chapter	Description
1	A description of the hardware used on Intel Compute Stick STK1AW32SC and STK1A32SC
2	A map of the resources of the Intel Compute Stick
3	The features supported by the BIOS Setup program

Typographical Conventions

This section contains information about the conventions used in this specification. Not all of these symbols and abbreviations appear in all specifications of this type.

Notes, Cautions, and Warnings



NOTE

Notes call attention to important information.



CAUTION

Cautions are included to help you avoid damaging hardware or losing data.

Other Common Notation

#	Used after a signal name to identify an active-low signal (such as USBP0#)
GB	Gigabyte (1,073,741,824 bytes)
GB/s	Gigabytes per second
Gb/s	Gigabits per second
KB	Kilobyte (1024 bytes)
Kb	Kilobit (1024 bits)
kb/s	1000 bits per second
MB	Megabyte (1,048,576 bytes)
MB/s	Megabytes per second
Mb	Megabit (1,048,576 bits)
Mb/s	Megabits per second
TDP	Thermal Design Power
Xxh	An address or data value ending with a lowercase h indicates a hexadecimal value.
x.x V	Volts. Voltages are DC unless otherwise specified.
*	This symbol is used to indicate third-party brands and names that are the property of their respective owners.

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1 Product Description

1.1 Overview

1.1.1 Version Summary

There are two different versions of this model of Intel® Compute Stick available which are summarized in Table 1. Unless otherwise noted in this document all features are available on all versions of the Intel Compute Stick.

Table 1. Version Summary

Version	Processor	OS Pre-installed
STK1AW32SC	Intel® Atom™ x5-Z8300 or x5-Z8330	Yes, Windows 10*
STK1A32SC	Intel® Atom™ x5-Z8300 or x5-Z8330	No

1.1.2 Feature Summary

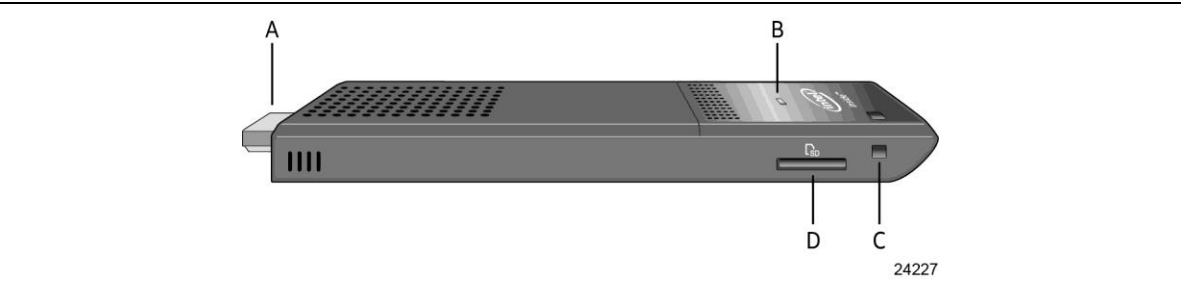
Table 2 summarizes the major features of the Intel Compute Stick.

Table 2. Feature Summary

Form Factor	113 millimeters by 38 millimeters by 12 millimeters (4.4488 inches by 1.4961 inches by 0.4724 inches)
Processor	<ul style="list-style-type: none">• Soldered-down Intel® Atom™ processor<ul style="list-style-type: none">– Integrated graphics– Integrated memory controller– Integrated PCH
Memory	<ul style="list-style-type: none">• Soldered-down single-channel DDR3L-RS 1600 MHz memory• 2 GB total memory
Graphics	<ul style="list-style-type: none">• Integrated graphics support with Intel® HD Graphics Technology:<ul style="list-style-type: none">– High Definition Multimedia Interface* (HDMI*)
Audio	Intel® High Definition (Intel® HD) Audio via the HDMI interface
Peripheral Interfaces	<ul style="list-style-type: none">• One full size USB 3.0 port• One full size USB 2.0 port
Storage	<ul style="list-style-type: none">• 32 GB soldered-down Embedded MultiMediaCard (eMMC) onboard storage• One Micro SD card slot (SDXC v3.0 with UHS-I support)
BIOS	<ul style="list-style-type: none">• Intel® BIOS resident in the Serial Peripheral Interface (SPI) Flash device• Support for Advanced Configuration and Power Interface (ACPI), Plug and Play, and System Management BIOS (SMBIOS)
Wireless LAN	Soldered-down Intel® Dual Band Wireless-AC module <ul style="list-style-type: none">• 802.11a/b/g/n, 802.11ac, Bluetooth* 4.0

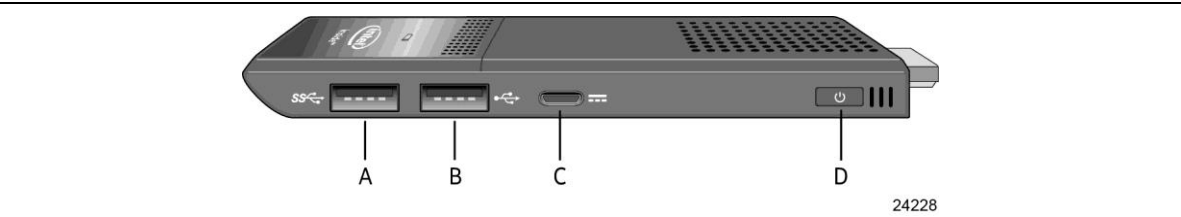
1.1.3 Location of Components

Figures 1 and 2 show the location of the components on the Intel Compute Stick.



Item	Description
A	HDMI Connector
B	Power LED
C	Security Loop
D	Micro SD Card Reader Slot

Figure 1. Left-Side View of Intel Compute Stick

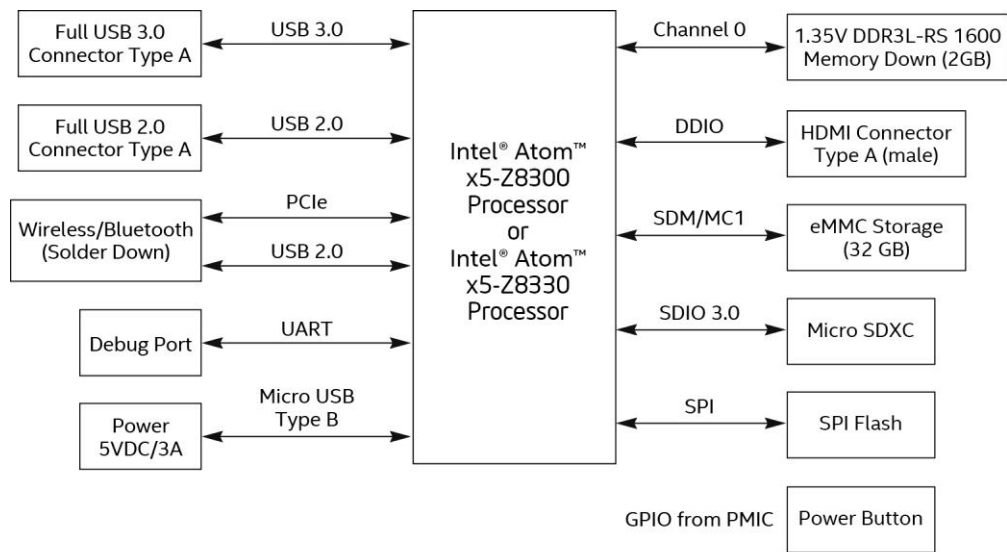


Item	Description
A	USB 3.0 Connector
B	USB 2.0 Connector
C	5 V DC Connector
D	Power On/Off Button

Figure 2. Right-Side View of Intel Compute Stick

1.1.4 Block Diagram

Figure 3 is a block diagram of the major functional areas of the Intel Compute Stick.



24230A

Figure 3. Block Diagram

1.2 Online Support

To find information about...

Intel Compute Stick

Visit this World Wide Web site:

<http://www.intel.com/computesticksupport>

1.3 Operating System Overview

The Intel Compute Stick STK1AW32SC has Windows 10 Home 32-bit pre-installed with all necessary drivers.

The Intel Compute Stick STK1A32SC supports the following Operating Systems (32-bit or 64-bit).

- Windows* 10 Home
- Windows 10 Pro
- Windows 10 Enterprise
- Windows 10 Education
- Windows 10 IoT Enterprise
- Windows 8.1
- Windows 8.1 Pro
- Windows 8.1 Enterprise
- Windows Embedded 8.1 Industry
- Windows Embedded 8.1 Pro

Installation of any of the above operating systems will require a powered USB hub, wired USB mouse and keyboard along with a USB flash drive or USB optical drive. The USB flash drive or USB optical drive will need the operating system installation media.



NOTE

Select either Windows 32-bit or Windows 64-bit in BIOS Setup for the type of operating system being installed.

To find information about...

Intel Compute Stick drivers

Visit this World Wide Web site:

<http://downloadcenter.intel.com>

1.4 Processor

The Intel Compute Stick has a soldered-down System-on-a-Chip (SoC), which consists of an Intel Atom Processor x5-Z8300 or x5-Z8330.

- Integrated Intel® HD Graphics
- Integrated memory controller
- Integrated PCH

1.5 System Memory

The Intel Compute Stick has soldered-down memory and supports the following memory features:

- DDR3L-RS 1600 MHz
- Single-channel memory
- 2 GB total memory

Refer to Section 2.1.1 on page 17 for information on the total amount of addressable memory.

1.6 System Storage

The Intel Compute Stick has soldered-down storage using an Embedded MultiMediaCard (eMMC) component. All Compute Sticks have 32 GB of total storage.



NOTE

STK1AW32SC uses a portion of this total storage for the operating system.

1.7 Processor Graphics Subsystem

The Intel Compute Stick supports graphics through Intel HD Graphics.

1.7.1 Integrated Graphics

The Intel Compute Stick supports integrated graphics via the processor.

1.7.1.1 Intel® High Definition (Intel® HD) Graphics

The Intel HD graphics controller features the following:

- HDMI 1.4b
- 3D graphics hardware acceleration supporting DirectX* 11.1, OpenCL 1.2, OGL ES 3.0, OpenGL 4.3
- Video decode hardware acceleration supporting H.263, H.264, H.265, MPEG2, MPEG4, JPEG, MVC, VC1, VP8 and VP9 formats
- Video encode hardware acceleration supporting H.263, H.264, JPEG and MVC formats

- High-Bandwidth Digital Content Protection (HDCP) 1.4/2.2 support for content protection

1.7.1.2 Video Memory Allocation

Intel® Dynamic Video Memory Technology (DVMT) is a method for dynamically allocating system memory for use as graphics memory to balance 2D/3D graphics and system performance. If your computer is configured to use DVMT, graphics memory is allocated based on system requirements and application demands (up to the configured maximum amount). When memory is no longer needed by an application, the dynamically allocated portion of memory is returned to the operating system for other uses.

1.7.1.3 High Definition Multimedia Interface* (HDMI*)

The HDMI port supports standard, enhanced, or high definition video, plus multi-channel digital audio on a single cable. The port is compatible with all ATSC and DVB HDTV standards and supports eight full range channels of lossless audio formats. The maximum supported resolution is 1920 x 1080 @ 60 Hz, 24 bpp. The HDMI port is compliant with the HDMI 1.4b specification.

1.7.1.3.1 Integrated Audio Provided by the HDMI Interfaces

The following audio technologies are supported by the HDMI 1.4b interfaces directly from the SoC:

- AC3 - Dolby* Digital
- Dolby Digital Plus
- LPCM, 192 kHz/16-bit or 176.4 KHz/24-bit, 8 Channel

1.8 USB

The Compute Stick has the following USB ports

- One full size USB 3.0 port with maximum current of 900 mA. The USB port is super-speed, high-speed, full-speed, and low-speed capable.
- One full size USB 2.0 port with maximum current of 500 mA. The USB port is high-speed, full-speed and low-speed capable.



NOTE

Computer systems that have an unshielded cable attached to a USB port may not meet FCC Class B requirements, even if no device is attached to the cable. Use a shielded cable that meets the requirements for full-speed devices.

1.9 Wireless LAN Subsystem

The wireless LAN subsystem consists of the following:

- Intel® Dual Band Wireless-AC 7265 module
- 1216 BGA soldered-down

For information about	Refer to
-----------------------	----------

LAN software and drivers	http://downloadcenter.intel.com
--------------------------	---

1.9.1 Wireless Network Module

The Dual Band Wireless-AC module provides hi-speed wireless connectivity with the following capabilities:

- 802.11a/b/g/n, 802.11ac
- 2.4 GHz, 5 GHz
- Two antennas
- Dual-mode Bluetooth 4.0

For information about	Refer to
-----------------------	----------

Obtaining WLAN software and drivers	http://downloadcenter.intel.com
-------------------------------------	---

1.10 Hardware Management Subsystem

The hardware management features enable the Compute Stick to be compatible with the Wired for Management (WfM) specification. The Compute Stick has several hardware management features, including thermal and voltage monitoring.

For information about	Refer to
-----------------------	----------

Wired for Management (WfM) Specification	www.intel.com/design/archives/wfm/
--	--

1.11 Power Management

Power management is implemented at several levels, including:

- Software support through Advanced Configuration and Power Interface (ACPI)
- Hardware support:
 - Power Input
 - Instantly Available PC technology

1.11.1 ACPI

ACPI gives the operating system direct control over the power management and Plug and Play functions of a computer. The use of ACPI with the Intel Compute Stick requires an operating system that provides full ACPI support. ACPI features include:

- Plug and Play (including bus and device enumeration)
- Power management control of individual devices

Table 3 lists the system states based on how long the power switch is pressed, depending on how ACPI is configured with an ACPI-aware operating system.

Table 3. Effects of Pressing the Power Switch

If the system is in this state...	...and the power switch is pressed for	...the system enters this state
Off (ACPI G2/G5 – Soft off)	Less than four seconds	Power-on (ACPI G0 – working state)
On (ACPI G0 – working state)	More than six seconds	Fail safe power-off (ACPI G2/G5 – Soft off)

Note: Depending on power management settings in the operating system.

1.11.1.1 System States and Power States

Under ACPI, the operating system directs all system and device power state transitions. The operating system puts devices in and out of low-power states based on user preferences and knowledge of how devices are being used by applications. Devices that are not being used can be turned off. The operating system uses information from applications and user settings to put the system as a whole into a low-power state.

Table 4 lists the power states supported by the Intel Compute Stick along with the associated system power targets. See the ACPI specification for a complete description of the various system and power states.

Table 4. Power States and Targeted System Power

Global States	Sleeping States	Processor States	Device States	Targeted System Power ^(Note 1)
G0 – working state	S0 – working	C0 – working	D0 – working state.	Full power
G2/S5	S5 – Soft off. Context not saved. Cold boot is required.	No power	D3 – no power except for wake-up logic.	Power < 5 W ^(Note 2)
G1 – sleeping state	S4 – Suspend to disk. Context saved to disk.	No power	D3 – no power except for wake-up logic.	Power < 5 W ^(Note 2)
G3 – mechanical off AC power is disconnected from the computer.	No power to the system.	No power	D3 – no power for wake-up logic.	No power to the system. Service can be performed safely.

Notes:

1. Total system power is dependent on the system configuration and peripherals powered by the system power supply.
2. Dependent on the standby power consumption of wake-up devices used in the system.

1.11.1.2 Wake-up Devices and Events

Table 5 lists the devices or specific events that can wake the Intel Compute Stick from specific states.

Table 5. Wake-up Devices and Events

Devices/events that wake up the system...	...from this sleep state	Comments
Power switch	S5	
RTC alarm	N/A	Wake from RTC is not supported
Wireless LAN	N/A	Wake from Wireless LAN is not supported
USB	N/A	Wake from USB is not supported
Bluetooth	N/A	Wake from Bluetooth is not supported

1.11.2 Hardware Support

Power management hardware features include:

- Wake from Power Button signal
- Instantly Available PC technology

1.11.2.1 Power Input

When resuming from an AC power failure, the Intel Compute Stick may return to the power state it was in before power was interrupted (on or off). The Intel Compute Stick's response can be set using the Last Power State feature in the BIOS Setup program's Boot menu.

2 Technical Reference

2.1 Memory Resources

2.1.1 Addressable Memory

The Intel Compute Stick utilizes up to 2 GB of addressable system memory. Typically the address space that is allocated for PCI Conventional bus add-in cards, PCI Express configuration space, BIOS (SPI Flash device), and chipset overhead resides above the top of DRAM (total system memory). On a system that has 2 GB of system memory installed, it is not possible to use all of the installed memory due to system address space being allocated for other system critical functions. These functions include the following:

- BIOS/SPI Flash device (64 Mb)
- Local APIC (19 MB)
- Direct Media Interface (40 MB)
- PCI Express configuration space (256 MB)
- SoC base address registers PCI Express ports (up to 256 MB)
- Integrated graphics shared memory (up to 512 MB; 64 MB by default)

The Intel Compute Stick provides the capability to reclaim the physical memory overlapped by the memory mapped I/O logical address space. Physical memory is remapped from the top of usable DRAM boundary to the 2 GB boundary to an equivalent sized logical address range located just above the 2 GB boundary. All installed system memory can be used when there is no overlap of system addresses.

2.2 Connectors

This section describes the connectors available on the Intel Compute Stick.

2.2.1 USB 3.0 Connector

The Intel Compute Stick has a single full size USB 3.0 connector that supports compliant USB devices. Bootable USB devices are supported.



Figure 4. USB 3.0 Connector

2.2.2 USB 2.0 Connector

The Intel Compute Stick has a single full size USB 2.0 connector that supports compliant USB devices. Bootable USB devices are supported.



Figure 5. USB 2.0 Connector



NOTE

It is recommended to only use a powered USB Hub with the Compute Stick's USB ports.

2.2.3 Micro SD Card Reader

The Intel Compute Stick has a microSecure Digital (SD) card reader that supports the Secure Digital eXtended Capacity (SDXC) format. Micro SD card 8 GB, 16 GB, 32 GB, 64 GB and 128 GB sizes are supported.



24226

Figure 6. Micro SD Card Reader

2.2.4 Power Adapter Connector

The Intel Compute Stick is powered through a 5V DC connector on the side. The maximum current rating is 3A.

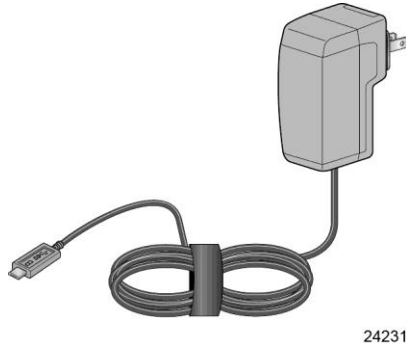


24229

Figure 7. Power Adapter Connector

2.2.5 Power Adapter

The Intel Compute Stick uses a 5V 3A AC to DC power adapter. The power adapter is connected to the Intel Compute Stick via a six foot cable with a USB Type B connector.



Item	Description
A	5V 3A Connector

Figure 8. Power Adapter



NOTE

The supplied power adapter with attached cable is required to power the Intel Compute Stick. Powering the Intel Compute Stick using any other power adapter and cable is not supported.

2.2.6 Security Loop

The Intel Compute Stick has a 3mm x 3mm opening in the chassis to allow for securing the Compute Stick.



Figure 9. Security Loop Opening

Use of a wire rope type cable that is >3mm can be used with crimps to secure the Compute Stick. One example is shown below. However, many different options are available via 3rd party suppliers.

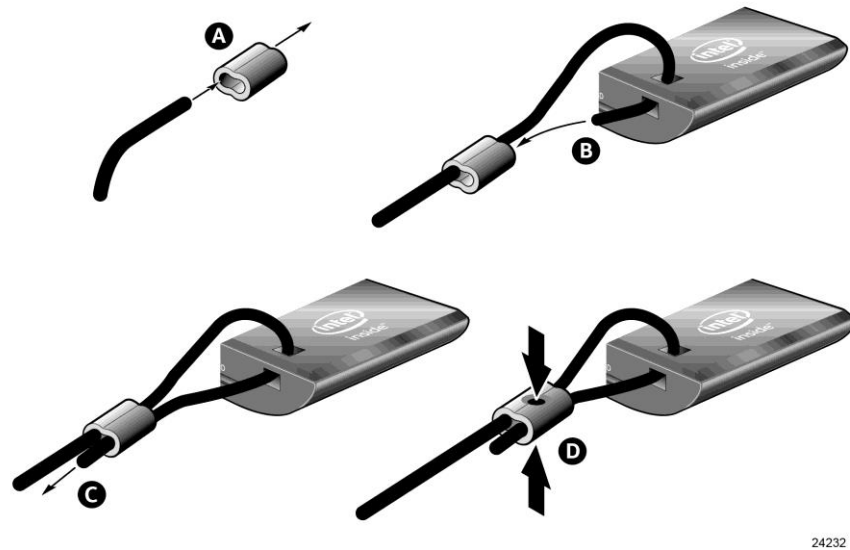


Figure 10. Security Loop Cable Example

2.3 Mechanical Considerations

2.3.1 Form Factor

Figure 11 illustrates the mechanical form factor for the Intel Compute Stick. Dimensions are given in millimeters.

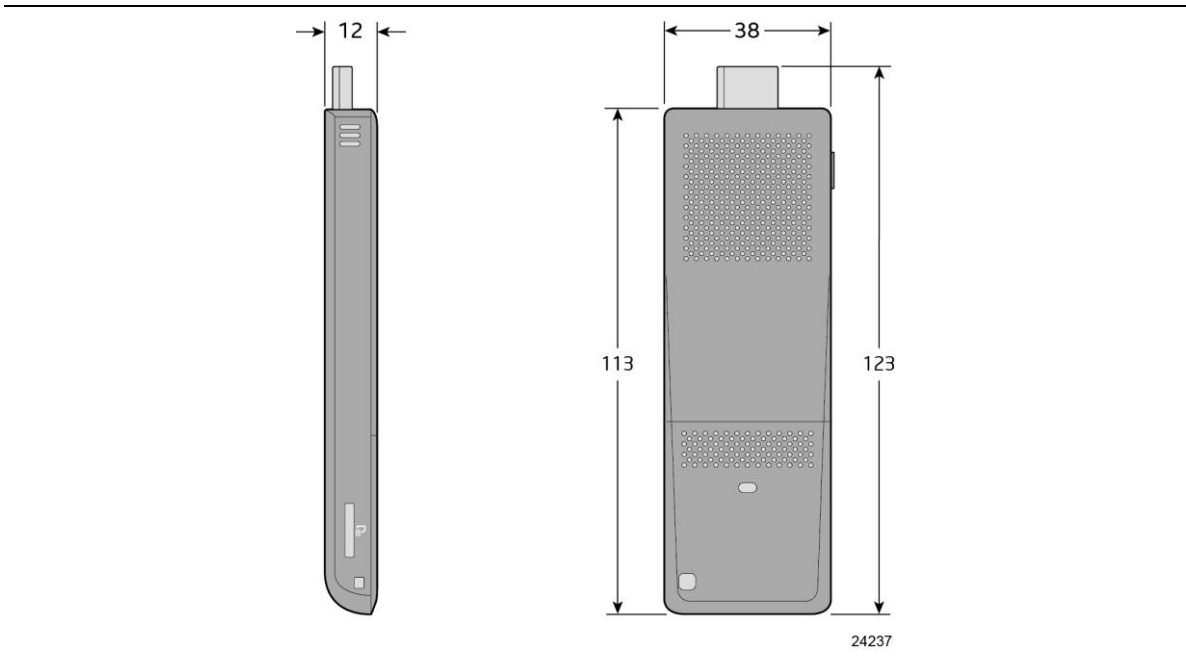


Figure 11. Intel Compute Stick Dimensions

Table 6. Intel Compute Stick Weight Information

Item	Weight
Compute Stick only	60.0g
Compute Stick in package	253.6g

2.4 Reliability

The Mean Time Between Failures (MTBF) prediction is calculated using component and subassembly random failure rates. The MTBF prediction is used to estimate repair rates and spare parts requirements. The MTBF for the Compute Stick is driven by the fan Mean Time to Failure (MTTF) of 46,855 hours.

2.5 Environmental

Table 7 lists the environmental specifications for the Intel Compute Stick.

Table 7. Environmental Specifications

Parameter	Specification		
Temperature			
Non-Operating	-40 °C to +60 °C		
Operating	0 °C to +35 °C The operating temperature of the Intel Compute Stick may be determined by measuring the air temperature from the outside of the chassis while the system is in operation ¹ .		
Shock			
Unpackaged	80cm drop		
Packaged	Half sine 2 millisecond		
	Product Weight (pounds)	Free Fall (inches)	Velocity Change (inches/s ²)
	<20	36	167
	21-40	30	152
	41-80	24	136
	81-100	18	118
Vibration			
Unpackaged	5 Hz to 20 Hz: 0.01 g ² Hz sloping up to 0.02 g ² Hz		
	20 Hz to 500 Hz: 0.02 g ² Hz (flat)		
Packaged	5 Hz to 40 Hz: 0.015 g ² Hz (flat)		
	40 Hz to 500 Hz: 0.015 g ² Hz sloping down to 0.00015 g ² Hz		

¹ Before attempting to operate the Intel Compute Stick, the overall temperature of the Intel Compute Stick must be above the minimum and below the maximum operating temperatures specified. The operating and non-operating environment must avoid condensing humidity.

3 Overview of BIOS Features

3.1 Introduction

The Intel Compute Stick uses an Intel BIOS that is stored in the Serial Peripheral Interface Flash Memory (SPI Flash) and can be updated using a disk-based program. The SPI Flash contains the BIOS Setup program, POST, the PCI auto-configuration utility, and Plug and Play support. The initial production BIOSs are identified as SCCHTAX5.86A.

The BIOS Setup program can be used to view and change the BIOS settings for the computer, and to update the system BIOS. The BIOS Setup program is accessed by pressing the <F2> key after the Power-On Self-Test (POST) memory test begins and before the operating system boot begins.

3.2 BIOS Flash Memory Organization

The Serial Peripheral Interface Flash Memory (SPI Flash) includes a 64 Mb (8192 KB) flash memory.

3.3 System Management BIOS (SMBIOS)

SMBIOS is a Desktop Management Interface (DMI) compliant method for managing computers in a managed network.

The main component of SMBIOS is the Management Information Format (MIF) database, which contains information about the computing system and its components. Using SMBIOS, a system administrator can obtain the system types, capabilities, operational status, and installation dates for system components. The MIF database defines the data and provides the method for accessing this information. The BIOS enables applications such as third-party management software to use SMBIOS. The BIOS stores and reports the following SMBIOS information:

- BIOS data, such as the BIOS revision level
- Fixed-system data, such as peripherals, serial numbers, and asset tags
- Resource data, such as memory size, cache size, and processor speed
- Dynamic data, such as event detection and error logging

Non-Plug and Play operating systems require an additional interface for obtaining the SMBIOS information. The BIOS supports an SMBIOS table interface for such operating systems. Using this support, an SMBIOS service-level application running on a non-Plug and Play operating system can obtain the SMBIOS information. Additional information can be found in the BIOS under the Additional Information header under the Main BIOS page.

3.4 BIOS Updates

The BIOS can be updated using either of the following utilities, which are available on the Intel World Wide Web site:

- Intel Express BIOS Update Utility, which enables automated updating while in the Windows environment. Using this utility, the BIOS can be updated from a file on a hard disk, a USB drive (a flash drive or a USB hard drive), or a CD-ROM, or from the file location on the Web.
- Intel F7 switch during POST allows a user to select where the BIOS .bio file is located and perform the update from that location/device.

All utilities verify that the updated BIOS matches the target system to prevent accidentally installing an incompatible BIOS.



NOTE

Review the instructions distributed with the upgrade utility before attempting a BIOS update.

For information about	Refer to
BIOS update utilities	http://www.intel.com/content/www/us/en/support/boards-and-kits/intel-compute-stick/000005961.html

3.4.1 Language Support

The BIOS Setup program and help messages are supported in US English. Check the Intel web site for support.

3.5 BIOS Recovery

It is unlikely that anything will interrupt a BIOS update; however, if an interruption occurs, the BIOS could be damaged. Table 8 lists the drives and media types that can and cannot be used for BIOS recovery. The BIOS recovery media does not need to be made bootable.

Table 8. Acceptable Drives/Media Types for BIOS Recovery

Media Type ^(Note)	Can be used for BIOS recovery?
Hard disk drive (connected to USB)	Yes
CD/DVD drive (connected to USB)	Yes
USB flash drive	Yes



NOTE

Supported file systems for BIOS recovery:

- NTFS (sparse, compressed, or encrypted files are not supported)
- FAT32
- FAT16
- FAT12
- ISO 9660

3.6 Boot Options

In the BIOS Setup program, the user can choose to boot from local storage or a removable drive. The default setting is for the local storage to be the first boot device.

3.6.1 Booting Without Attached Devices.

For use in embedded applications, the BIOS has been designed so that after passing the POST, the operating system loader is invoked even if the following devices are not present:

- Video Display
- Keyboard
- Mouse

3.6.2 BIOS POST Hotkeys

The following hot keys are supported during boot.

- [F2] Enter BIOS Setup
- [F7] Update BIOS
- [F8] Activate Windows Recovery Mode
- [F10] Enter Boot Menu

3.6.3 Changing the Default Boot Device During POST

Pressing the <F10> key during POST causes a boot device menu to be displayed. This menu displays the list of available boot devices. Table 9 lists the boot device menu options.

Table 9. Boot Device Menu Options

Boot Device Menu Function Keys	Description
<↑> or <↓>	Selects a default boot device
<Enter>	Exits the menu, and boots from the selected device
<Esc>	Exits the menu and boots according to the boot priority defined through BIOS setup

3.6.4 Power Button Menu

The Power Button Menu is accessible via the following sequence:

1. System is in S5 (not G3)
2. User pushes the power button and holds it down for approximately 3 seconds
3. Release immediately
4. User releases the power button before the 4-second shutdown override

If this boot path is taken, the BIOS will use default settings, ignoring settings in VPD where possible.

At the point where Setup Entry/Boot would be in the normal boot path, the BIOS will display the following prompt and wait for a keystroke:

- [ESC] Normal Boot
- [F2] Intel BIOS Setup
- [F4] BIOS Recovery
- [F7] Update BIOS
- [F10] Enter Boot Menu

3.7 BIOS Error Messages

Table 10 lists the error messages and provides a brief description of each.

Table 10. BIOS Error Messages

Error Message	Explanation
CMOS Battery Low	The battery may be losing power. Replace the battery soon.
CMOS Checksum Bad	The CMOS checksum is incorrect. CMOS memory may have been corrupted. Run Setup to reset values.
No Boot Device Available	System did not find a device to boot.

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